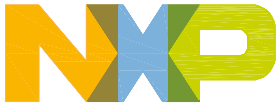


4X
0.2 | H | A–B | D

4X 44 TIPS
0.2 | C | A–B | D

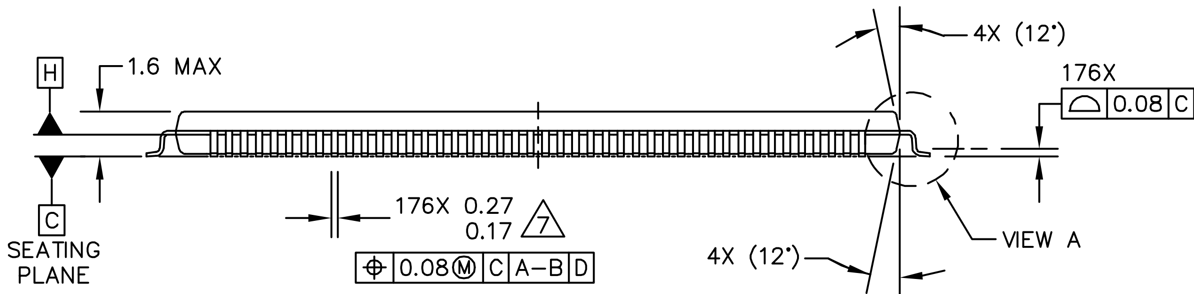
PIN 1
IDENT.

176
133
1
132
44
89
45
88

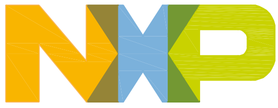
3X VIEW B

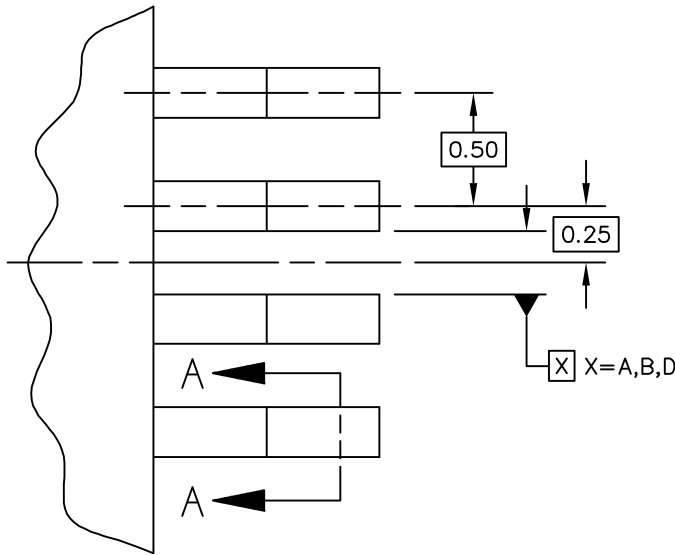
B 4
A 4
D 4

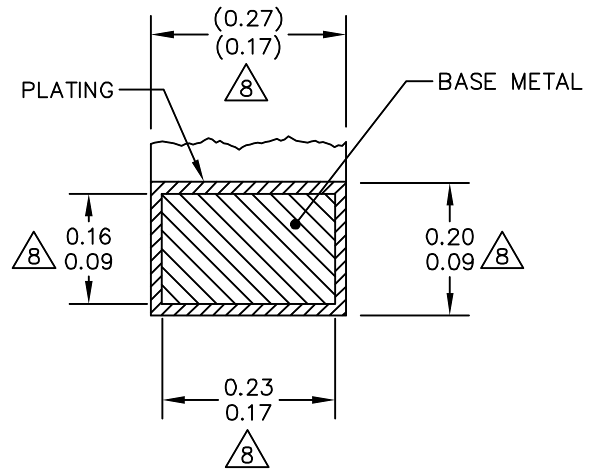
6
5
24
26
12
13

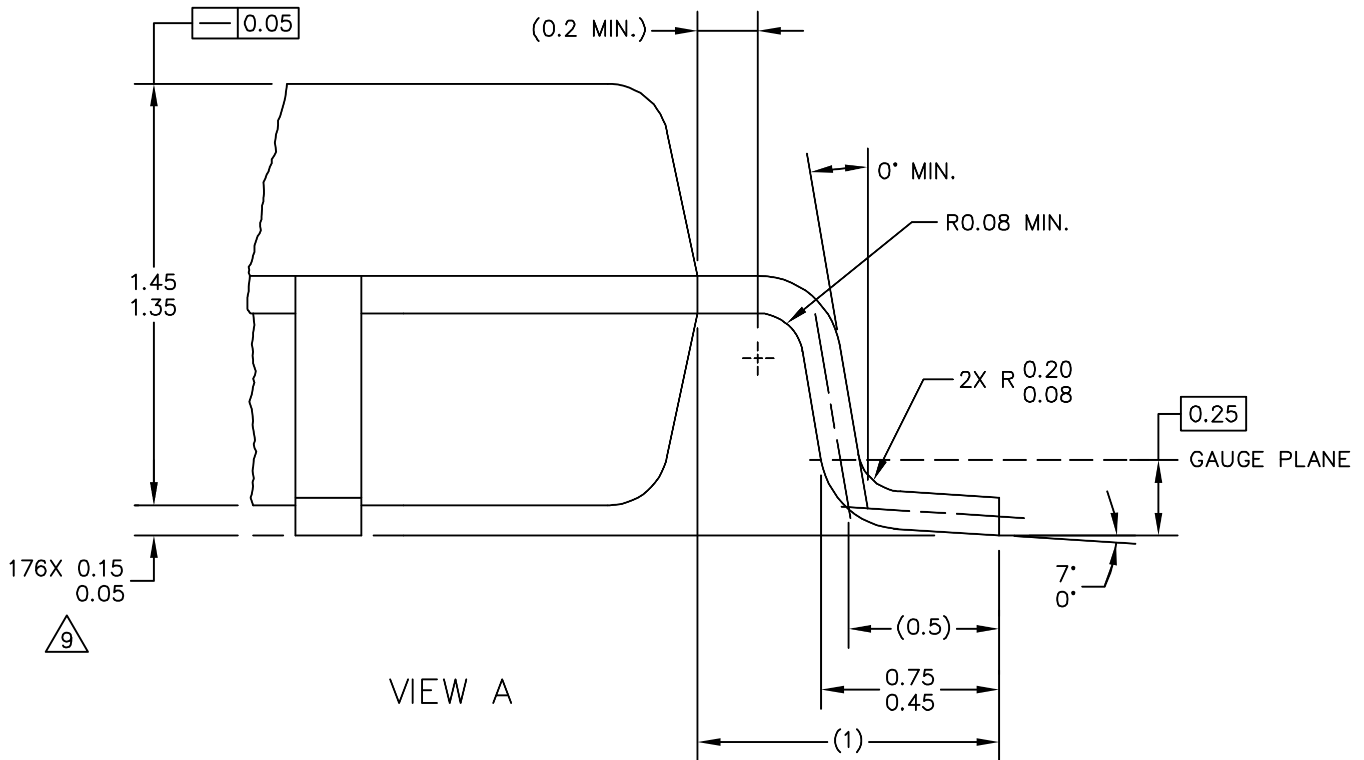


© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 176 LD LQFP, 24 X 24 PKG, 0.5 PITCH, 1.4 THICK	DOCUMENT NO: 98ASS23479W	REV: D
	STANDARD: JEDEC MS-026 BGA	
	SOT506-2	27 JAN 2016



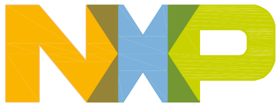






© NXP SEMICONDUCTORS N. V.
ALL RIGHTS RESERVED

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 176 LD LQFP, 24 X 24 PKG, 0.5 PITCH, 1.4 THICK	DOCUMENT NO: 98ASS23479W REV: D
	STANDARD: JEDEC MS-026 BGA
	SOT506-2 27 JAN 2016



NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M–1994.

2. DIMENSIONS IN MILLIMETERS.

3. DATUM PLANE H IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.

4. (△) DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.

5. (△) THIS DIMENSIONS TO BE DETERMINED AT SEATING PLANE, DATUM C.

6. (△) THIS DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 PER SIDE. THIS DIMENSIONS INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE H.

7. (△) THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED 0.35. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD 0.07.

8. (△) THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 MM AND 0.25 MM FROM THE LEAD TIP.

9. (△) DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

© NXP SEMICONDUCTORS N. V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 176 LD LQFP, 24 X 24 PKG, 0.5 PITCH, 1.4 THICK	DOCUMENT NO: 98ASS23479W	REV: D
	STANDARD: JEDEC MS-026 BGA	
	SOT506-2	27 JAN 2016